

OCtoPus 3iP

SERVER BASED ON OCP PRINCIPLES

21-inch - 10U - 3 Nodes - 6 CPUs chassis - Front IO

Key Features



21-inch - 10U / 6 CPUs
- Front IO



Dual INTEL® XEON® 3rd
Generation Scalable
Processors family
Socket P+



48x DDR4 @ 3200MHz



PCIe lanes Gen.4



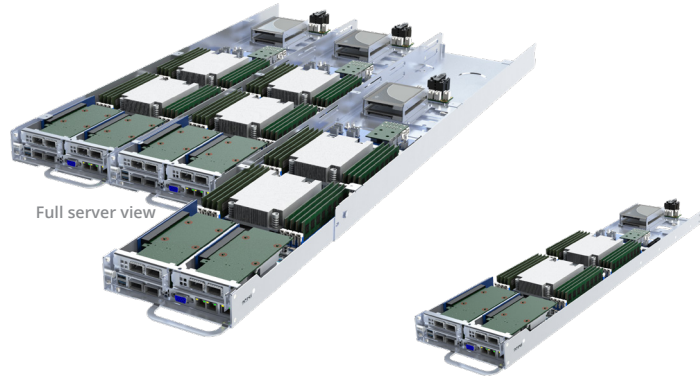
OCP technology 12V
DC



IPMI with ASPEED®
AST2500



Immersion Cooling



Full server view

View of a single node

3rd Gen Intel® Xeon® Scalable Processors

The OCtoPus 3iP is built with the latest Intel® Xeon® Scalable Processors, and designed for the demand of high scalability, high density computing, and wide range of existing and emerging workloads. 3rd Gen Intel® Xeon® Scalable processors offer a balanced architecture with built-in acceleration and advanced security capabilities, designed through decades of innovation for the most in-demand workload requirements.

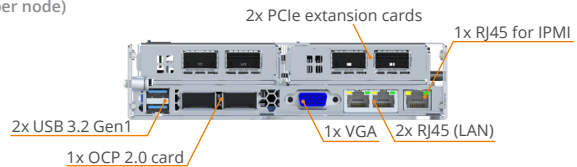
Certified by the Solar Impulse Foundation

To address sustainability challenges while enabling economic growth Bertrand Piccard, serial explorer, initiator and visionary behind Solar Impulse has identified with its Foundation, 1000+ clean and profitable solutions including the OCtoPus server solution since October 2021.

Cloud and Enterprise Made Flexible

The latest 3rd Gen Intel® Xeon® Scalable processors are built upon years of cloud innovation, tuned to your unique needs with built-in AI and Intel® Crypto Acceleration and advanced security capabilities.

Front I/O view (per node)



Server overview



SPECIFICATIONS

System	Model	OCtoPus 3iP
	Form Factor	21-inch 1OpenU
	Nodes	6 CPUs
	Dimension	845 x 537 x 43mm 33"x 21" x 1.7"
Storage	Internal type	Up to 2x 2.5" SATA/SAS/Gen4 NVMe per node
Motherboard	CPU	Per node: 2x Socket P+ (LGA 4189) Intel® XEON® 3rd Generation Scalable Processors family
	Chipset	Intel® C621A Express Chipset
	Expansion slots per node	2x PCIe Gen4 x16 Half-length low-profile slot
	BMC	Aspeed® AST2500
Memory	Total Slots	48 (8-channel, 8-DIMM per CPU) DDR4 memory supported only
	Capacity per DIMM	Maximum up to 128GB (with RDIMM / LRDIMM modules) Maximum up to 256GB (with 3DS RDIMM / LRDIMM modules)
	Memory Speed	Up to 3200 MHz
Network		Per node: 2x RJ45 10GLAN by Intel® X710-AT2 1x Dedicated management port 1x OCP 2.0 Mezzanine (via 1x PCIe Gen3 x8) Options available: 25GbE (SFP28) 100GbE (QSFP56 / QSFP28) 200GbE (QSFP56)
Front I/O	Ports	Per node: 2x USB 3.0 1x VGA 2x RJ45 (10GbE) 2x ports via OCP 2.0 card 1x RJ45 dedicated IPMI
	Switch/LED	Per node: 1x Power button with LED 1x UID button with LED 1x Reset button with LED 3x LAN Status LED 3x LAN Speed LED
Management Solution	Out of Band Remote Management	BMC Remote control based on Aspeed® AST2500 remote management controller (Power Control Configuration, Chassis Identify, Boot Option, iKVM, BMC Account Configuration)
Power Input	Type	OCP technology 12V DC